

[ABSTRACT]

SILICON BASED CONDENSER MICROPHONE AND PACKAGING METHOD FOR
THE SAME

Disclosed are a silicon based condenser microphone and a packaging method for the silicon based condenser microphone. The silicon based condenser microphone comprises a metal case, and a board which is mounted with a MEMS microphone chip and an ASIC chip having a electric voltage pump and a buffer IC and is formed with a connecting pattern for bonding with the metal case, wherein the connecting pattern is welded to the metal case. The method for packaging a silicon based condenser microphone comprises the steps of inputting a board which is mounted with a MEMS chip and an ASIC chip and is formed with a connecting pattern; inputting a metal case, aligning the metal case on the connecting pattern of the board, and welding an opened end of the metal case to the connecting pattern of the board. Thus, the metal case is welded to the board by the laser.

[Figure 1]